

WHAT IS CLAIMED IS:

1. A slurry for polishing copper-based metal
containing a silica polishing material, an oxidizing agent,
an amino acid, a triazole-based compound and water,
5 wherein a content ratio of said amino acid to said
triazole-based compound (amino acid / triazole-based
compound (weight ratio)) is 5 to 8.

2. The slurry for polishing copper-based metal
10 according to Claim 1, wherein said amino acid is glycine.

3. The slurry for polishing copper-based metal
according to Claim 1, wherein said triazole-based compound
is 1, 2, 4-triazole or its derivative.

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4. The slurry for polishing copper-based metal
according to Claim 1, wherein a content of said triazole-
based compound is not less than 0.05 % by weight but not
greater than 0.5 % by weight.

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5. The slurry for polishing copper-based metal
according to Claim 1, wherein a pH value of said slurry is
in a range of 5 to 7.

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6. The slurry for polishing copper-based metal
according to Claim 1, wherein said silica polishing

material is colloidal silica.